

LAYER NUMBER	IMP	TYP		LAYOUT NAME	SIGNAL USE	SIZE		
1	100 Ohm	SIGNAL	S1	TOP		12		4.PRESSING
2		GND	Plane	GND1		16		3.PRESSING
3	100 Ohm	SIGNAL	S2	SIG1	MGT_AVAGO	16		2.PRESSING
4		GND	Plane	GND2		16		1. PRESSING
5	100 Ohm	SIGNAL	S3	SIG2	MGT_LOOPB	16		
6		GND	Plane	GND3		16		
7	100 Ohm	SIGNAL	S4	SIG3	CONF_I/O	16		
8		GND	Plane	GND4		16		
9	100 Ohm	SIGNAL	S5	SIG4	Parallel_I/O	16		
10		GND	Plane	GND5		70		
11		PWR	Plane	PWR1	MGTAVTT,BoardL.	70		
12		PWR	Plane	PWR2	VCCINT,12V,BoardL.	105		
13		PWR	Plane	PWR3	GND	105		
14		PWR	Plane	PWR4	MGTAVCC,BoardL.	70		
15		GND	Plane	GND6		70		
16	100 Ohm	SIGNAL	S6	SIG5	Parallel_I/O	16		
17		GND	Plane	GND7		16		
18	100 Ohm	SIGNAL	S7	SIG6	Parallel_I/O	16		
19		GND	Plane	GND8		16		
20	100 Ohm	SIGNAL	S8	SIG7	Parallel_I/O	16		
21		GND	Plane	GND9		16		1.PRESSING
22	100 Ohm	SIGNAL	S9	SIG8	CLOCK	16		2.PRESSING
23		GND	Plane	GND10		16		3.PRESSING
24	100 Ohm	SIGNAL	S10	BOT		12		4.PRESSING



Micro Via 350um/125um stacked
 Via50-25-75 500um/250um
 Burried Via 450um/200um

diff.Traces 100/125/100 um TOP/BOT 100 Ohm
 diff.Traces 90/120/90 um Inner Lay 100 Ohm
 single Traces 200 um TOP/BOT 50 Ohm